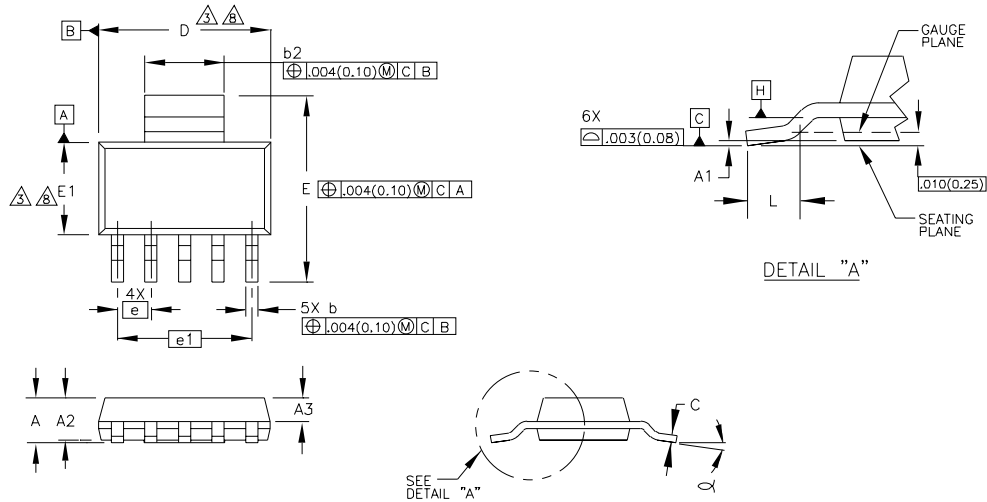


Package Number 364 - 5-Lead SOT-223



DIM	INCHES		MILLIMETERS		N	E
	MIN.	MAX.	MIN.	MAX.		
A	—	.071	—	1.80		
A1	.001	.004	0.02	0.10		
A2	.061	.065	1.55	1.65		
A3	.034	.036	0.87	0.91		
b	.016	.020	0.41	0.51	4,5	
b2	.116	.120	2.95	3.05		
C	.009	.013	0.24	0.32	5	
D	.254	.258	6.45	6.55	3	
E	.270	.286	6.86	7.26		
E1	.136	.140	3.45	3.55	3	
e	.050 BASIC		1.27 BASIC			
e1	.200 BASIC		5.08 BASIC			
L	.036	.045	0.91	1.14		
N	5		5		10	

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M - 1994.
2. CONTROLLING DIMENSION IN INCHES.
3. DIMENSIONS "D" & "E1" ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS, AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND THE BOTTOM OF THE PLASTIC BODY.
4. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION.
5. DIMENSION "b" & "c" APPLY TO SOLDER PLATED LEADS.
6. INTERLEAD FLASH ALLOW .008 INCH MAX.
7. GATE BURR/PROTRUSION MAX .006 INCH.
8. DATUMS A AND B ARE TO BE DETERMINED AT DATUM H.
9. PACKAGE DIMENSIONS PER JEDEC OUTLINE DRAWING TO-261, ISSUE B, DATED FEB. 1999. THIS VARIATION IS NOT YET INCLUDED.
10. N IS THE MAXIMUM NUMBER OF LEADS.

PACKAGE NUMBER: ZZ364	REV.: A
JEDEC NUMBER: NONE	

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